

HFP9N50-VB Datasheet

N-Channel 500V (D-S)Power MOSFET

PRODUCT SUMMARY		
V_{DS} (V)	500	
$R_{DS(on)}$ (Ω)	$V_{GS} = 10\text{ V}$	0.660
Q_g (Max.) (nC)	81	
Q_{gs} (nC)	20	
Q_{gd} (nC)	36	
Configuration	Single	

FEATURES

- Lower Gate Charge Q_g Results in Simpler Drive Requirements
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage
- Compliant to RoHS Directive 2002/95/EC



ABSOLUTE MAXIMUM RATINGS ($T_C = 25\text{ }^\circ\text{C}$, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-Source Voltage	V_{DS}	500	V	
Gate-Source Voltage	V_{GS}	± 20		
Continuous Drain Current	V_{GS} at 10 V	$T_C = 25\text{ }^\circ\text{C}$	13	A
		$T_C = 100\text{ }^\circ\text{C}$	8.1	
Pulsed Drain Current ^a	I_{DM}	50		
Linear Derating Factor		2.0	W/ $^\circ\text{C}$	
Single Pulse Avalanche Energy ^b	E_{AS}	560	mJ	
Avalanche Current ^a	I_{AR}	13	A	
Repetitive Avalanche Energy ^a	E_{AR}	25	mJ	
Maximum Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	250	W
Peak Diode Recovery dV/dt ^c		dV/dt	9.2	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$	
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d		
Mounting Torque	6-32 or M3 screw	10		lbf · in
		1.1	N · m	

Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Starting $T_J = 25\text{ }^\circ\text{C}$, $L = 5.7\text{ mH}$, $R_g = 25\text{ }\Omega$, $I_{AS} = 14\text{ A}$, $dV/dt = 7.6\text{ V/ns}$ (see fig. 12a).
- $I_{SD} \leq 14\text{ A}$, $dI/dt \leq 250\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DS}$, $T_J \leq 150\text{ }^\circ\text{C}$.
- 1.6 mm from case.

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	R_{thJA}	-	62	°C/W
Case-to-Sink, Flat, Greasd Surface	R_{thCS}	0.50	-	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.50	

SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)									
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT		
Static									
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$		500	-	-	V		
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$, $I_D = 1\text{ mA}$		-	0.55	-	V/°C		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$		2.0	-	4.0	V		
Gate-Source Leakage	I_{GSS}	$V_{GS} = \pm 20\text{ V}$		-	-	± 100	nA		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 500\text{ V}, V_{GS} = 0\text{ V}$		-	-	25	μA		
		$V_{DS} = 400\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	250			
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$	$I_D = 8.4\text{ A}^b$	-	0.660	-	Ω		
Forward Transconductance	g_{fs}	$V_{DS} = 50\text{ V}, I_D = 8.4\text{ A}$		8.1	-	-	S		
Dynamic									
Input Capacitance	C_{iss}	$V_{GS} = 0\text{ V}, V_{DS} = 25\text{ V}, f = 1.0\text{ MHz}$, see fig. 5		-	1910	-	pF		
Output Capacitance	C_{oss}			-	290	-			
Reverse Transfer Capacitance	C_{rss}			-	11	-			
Output Capacitance	C_{oss}	$V_{GS} = 0\text{ V}$	$V_{DS} = 1.0\text{ V}, f = 1.0\text{ MHz}$	-	2730	-	pF		
			$V_{DS} = 400\text{ V}, f = 1.0\text{ MHz}$	-	82	-			
Effective Output Capacitance	$C_{oss\text{ eff.}}$	$V_{DS} = 0\text{ V to } 400\text{ V}^c$		-	160	-			
Total Gate Charge	Q_g	$V_{GS} = 10\text{ V}$		-	-	81	nC		
Gate-Source Charge	Q_{gs}			$I_D = 14\text{ A}, V_{DS} = 400\text{ V}$, see fig. 6 and 13 ^b		-		-	20
Gate-Drain Charge	Q_{gd}					-		-	36
Turn-On Delay Time	$t_{d(on)}$	$V_{GS} = 10\text{ V}$		-	15	-	ns		
Rise Time	t_r			$V_{DD} = 250\text{ V}, I_D = 14\text{ A}, R_g = 7.5\text{ }\Omega$, see fig. 10 ^b		-		39	-
Turn-Off Delay Time	$t_{d(off)}$					-		39	-
Fall Time	t_f					-		31	-
Drain-Source Body Diode Characteristics									
Continuous Source-Drain Diode Current	I_S	MOSFET symbol showing the integral reverse p - n junction diode 		-	-	13	A		
Pulsed Diode Forward Current ^a	I_{SM}			-	-	56			
Body Diode Voltage	V_{SD}	$T_J = 25\text{ }^\circ\text{C}, I_S = 14\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	1.5	V		
Body Diode Reverse Recovery Time	t_{rr}	$T_J = 25\text{ }^\circ\text{C}, I_F = 14\text{ A}, T_J = 125\text{ }^\circ\text{C}, dI/dt = 100\text{ A}/\mu\text{s}^b$		-	370	550	ns		
Body Diode Reverse Recovery Charge	Q_{rr}			-	4.4	6.5	μC		
Body Diode Reverse Recovery Current	I_{RRM}			-	21	31	A		
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L_S and L_D)							

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width $\leq 300\text{ }\mu\text{s}$; duty cycle $\leq 2\%$.
- c. $C_{oss\text{ eff.}}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS} .

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Fig. 1 - Typical Output Characteristics



Fig. 3 - Typical Transfer Characteristics



Fig. 2 - Typical Output Characteristics



Fig. 4 - Normalized On-Resistance vs. Temperature



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Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage



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Fig. 7 - Typical Source-Drain Diode Forward Voltage



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Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



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Fig. 8 - Maximum Safe Operating Area



Fig. 9 - Maximum Drain Current vs. Case Temperature



Fig. 10a - Switching Time Test Circuit



Fig. 10b - Switching Time Waveforms



Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



Fig. 12a - Unclamped Inductive Test Circuit



Fig. 12b - Unclamped Inductive Waveforms



Fig. 12c - Maximum Avalanche Energy vs. Drain Current



Fig. 13a - Basic Gate Charge Waveform



Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

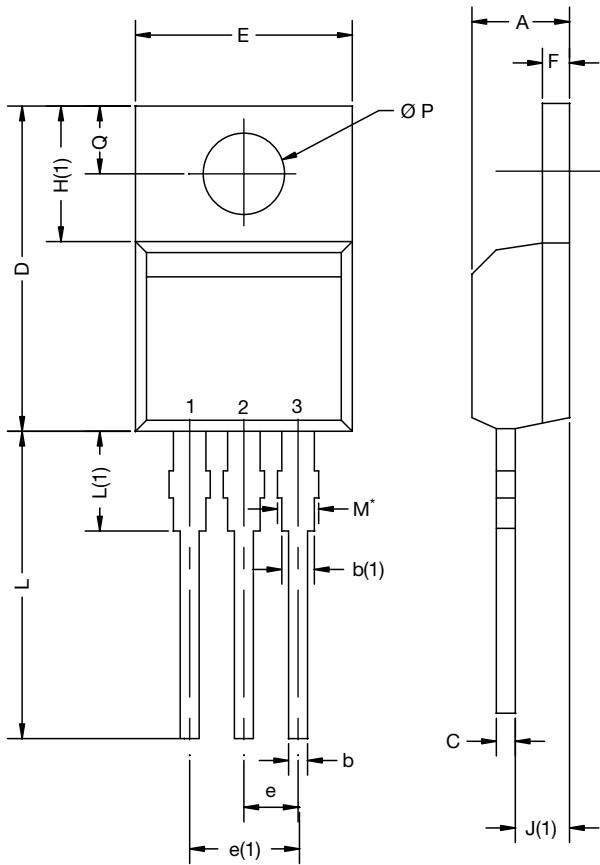


Note

a. $V_{GS} = 5 V$ for logic level devices

Fig. 14 - For N-Channel

TO-220AB



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
$\varnothing P$	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

ECN: X15-0364-Rev. C, 14-Dec-15
DWG: 6031

Note

- M^* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

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